

**Product / Package Information**

Package	LF CSP
Body Size (mm)	3 X 3 X 0.85
Lead Count	16
Terminal Finish	100 Sn

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.41E-02	93.70	937000	38.33	383321
Thermosets	Epoxy Resin	Proprietary	4.53E-04	3.00	30000	1.23	12273
Thermosets	Phenol Resin	Proprietary	4.53E-04	3.00	30000	1.23	12273
Other inorganic materials	Carbon Black	1333-86-4	4.53E-05	0.30	3000	0.12	1227
Subtotal			1.51E-02	100.00	1000000	40.91	409094

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.75 E-02	96.40	963989	47.32	473234
Copper & its alloys	Iron	7439-89-6	4.53 E-04	2.50	25006	1.23	12276
Copper & its alloys	Zinc	7440-66-6	1.09 E-04	0.60	6004	0.29	2947
Copper & its alloys	Phosphorus	7723-14-0	9.06 E-05	0.50	5001	0.25	2455
Subtotal			1.81 E-02	100.00	1000000	49.09	490912

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.53 E-05	100.0	1000000	0.12	1227

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	8.63 E-04	100.0	1000000	2.34	23377

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	8.63 E-05	100.0	1000000	0.23	2338

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	2.59 E-03	100.0	1000000	7.01	70130

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.55 E-05	70.00	700000	0.20	2045
Other organic materials	Epoxy Resin	9003-36-5 / 30583-72-3	2.16 E-05	20.00	200000	0.06	584
Other organic materials	t-butyl phenyl glycidyl ether	3101-60-3	8.09 E-06	7.50	75000	0.02	219
Other organic materials	Phenolic hardener	92-88-6	1.62 E-06	1.50	15000	0.00	44
Other organic materials	Butyl cellosolve acetate	112-07-2	1.08 E-06	1.00	10000	0.00	29
Subtotal			1.08 E-04	100.0	1000000	0.29	2922

<b>Package Totals</b>			<b>Weight (g)</b> 3.69 E-02			<b>Percentage (%)</b> 100	<b>PPM</b> 1000000
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Control ID: MS012320DPKG4915

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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